Corporate & Foundry
23155 Kashiwa Court, Torrance, CA 90505
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Global Communication Semiconductors, LLC

Process Engineer - Backend

Job Req.	#0786
Department:	Manufacturing Engineering
Status:	Full-Time / Salaried
Shift:	Monday – Friday (8am – 5pm)
Pay:	$65,000 - $90,000 annually
Hiring Manager:	Wendy Le

Job Description

This position is primarily responsible for the following:

- Process control and development for die singulation including but not limited to wafer mounting, scribe, break, wafer cleaning, expansion, die pick, and thickness verification.
- Operator training
- Documentation upkeep
- Tool ownership of scribe and break tools and assist EQUIP tech on troubleshooting and be contact point for vendors
- Support other backend processes such as incoming inspection, wafer cleaning, defect identification, and other tasks as needed by backend module manager
- Engineer Cross training tools between backside and Backend.
- Performs other related duties as assigned by management.

Job Requirements

- Bachelor's Degree (BS) of engineering field (Chemical, Mechanical, material, electrical)
- Experience with 1 or more years of industrial experience and/or training in wafer scribe and break for GaAs and InP substrates.
- Must have clean room and hands on wafer processing experience
- Strong knowledge in optical inspection and wafer scribe/break.
- Good written and verbal communication skills.
- Computer skills required: Development Software; Microsoft Office; and Eyelit